

Title (en)

Light emitting device, method for fabricating light emitting device, and light emitting device package

Title (de)

Lichtemittierende Vorrichtung, Verfahren zur Herstellung der lichtemittierende Vorrichtung und lichtemittierende Vorrichtungspaket

Title (fr)

Dispositif électroluminescent, son procédé de fabrication et paquet de dispositif électroluminescent

Publication

EP 2372792 A3 20150429 (EN)

Application

EP 11159085 A 20110321

Priority

KR 20100027773 A 20100329

Abstract (en)

[origin: EP2372792A2] Provided are a light emitting device, a method for fabricating the light emitting device, a light emitting device package, and a lighting system. The light emitting device includes a first conductive type semiconductor layer having a first top surface and a second top surface under the first top surface, an active layer on the first top surface of the first conductive type semiconductor layer, a second conductive type semiconductor layer on the active layer, a first electrode on the second top surface of the first conductive type semiconductor layer, an intermediate refractive layer on the second top surface of the first conductive type semiconductor layer, and a second electrode connected to the second conductive type semiconductor layer.

IPC 8 full level

H01L 33/44 (2010.01); **H01L 33/42** (2010.01)

CPC (source: EP US)

H01L 33/42 (2013.01 - EP US); **H01L 33/20** (2013.01 - EP US); **H01L 33/38** (2013.01 - EP US); **H01L 33/44** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

C-Set (source: EP US)

1. **H01L 2224/48091** + **H01L 2924/00014**
2. **H01L 2924/181** + **H01L 2924/00012**

Citation (search report)

- [X] EP 1953838 A2 20080806 - NICHIA CORP [JP]
- [X] US 2001042860 A1 20011122 - HATA TOSHIO [JP], et al
- [X] US 2008290364 A1 20081127 - KAMIYA MASAO [JP], et al
- [X] US 2009212312 A1 20090827 - TSAI TZONG-LIANG [TW], et al

Cited by

EP3392919A1; US10276751B2; US10593840B2; US10978617B2; US11817529B2; US12068437B2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 2372792 A2 201111005; **EP 2372792 A3 20150429**; **EP 2372792 B1 20161130**; CN 102208509 A 20111005; CN 102208509 B 20141231; KR 101054983 B1 20110805; US 2011233590 A1 20110929; US 8564008 B2 20131022

DOCDB simple family (application)

EP 11159085 A 20110321; CN 201110078842 A 20110328; KR 20100027773 A 20100329; US 201113073381 A 20110328